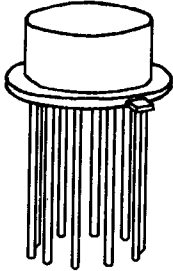
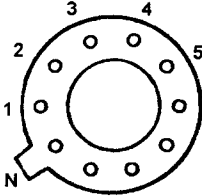
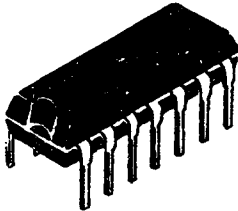
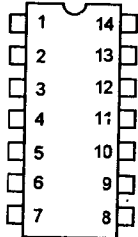
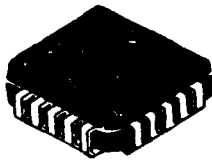
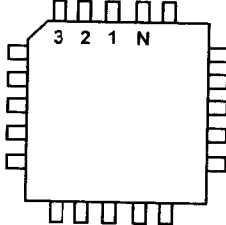
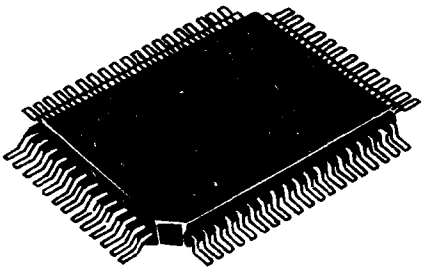
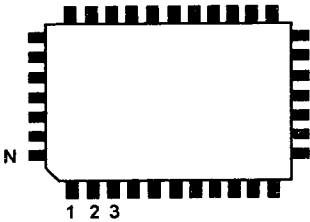
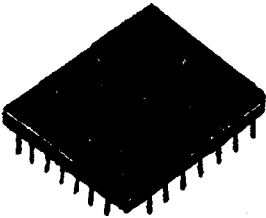
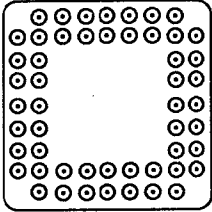
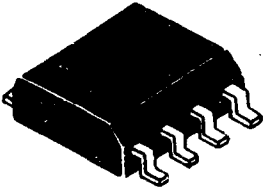
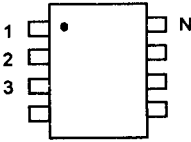
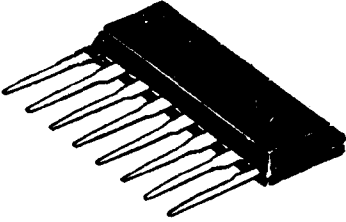
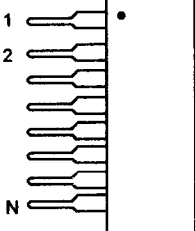
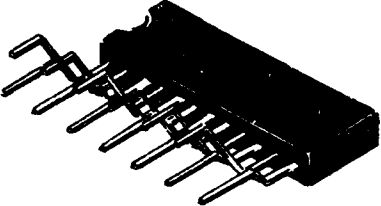
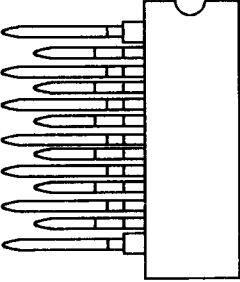
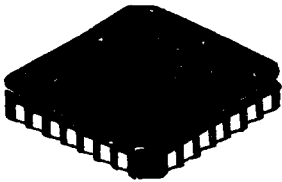
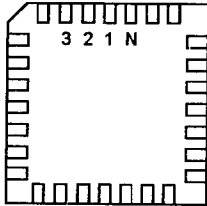


本手册所用芯片封装形式

封装形式	名称	外形图	引出端排列图
CAN (Metal Can Package)	金属圆 壳封装		 (底视图)
DIP (Dual Inline Package)	双列 直插 封装		 (顶视图)
LDCC (Leaded Chip Carrier)	引线 片载		 (顶视图)
PLCC (Plastic Leaded Chip Carrier)	塑料 引线 片载	(同 LDCC)	(同 LDCC)

封装形式	名称	外形图	引出端排列图
QFP (Quad Flat Package)	四边引线扁平封装		 (顶视图)
PGA (Pin Grid Array)	插针阵列		 (底视图)
SOIC (Small Outline Integrated Circuit)	小外形封装		 (顶视图)
SIP (Single Inline Package)	单列直插封装		 (顶视图)
ZIP (Zig Zag Inline Package)	Z形引线单列直插封装		 (顶视图)

封装形式	名称	外形图	引出端排列图
LLCC (Leadless Chip Carrier)	无引 线片 载		 (顶视图)

